

## Wireless, Passive Ceramic Strain Sensors for Turbine Engine Applications

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# Outline

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- Strain Sensors State of the Art
- Objectives
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- Summary



## Motivation – applications of turbines

■ Turbine engines – key for energy generation and propulsion

| Description                             | 2007      |  |  |  |  |  |  |  |
|---|-----------|--|--|--|--|--|--|--|
| Net Generation (thousand megawatthours) |           |  |  |  |  |  |  |  |
| Coal <u>[1]</u>                         | 2,016,456 |  |  |  |  |  |  |  |
| Petroleum[2]                            | 65,739    |  |  |  |  |  |  |  |
| Natural Gas                             | 896,590   |  |  |  |  |  |  |  |
| Other Gases[3]                          | 13,453    |  |  |  |  |  |  |  |
| Nuclear                                 | 806,425   |  |  |  |  |  |  |  |
| Hydroelectric Conventional[4]           | 247,510   |  |  |  |  |  |  |  |
| Other Renewables[5]                     | 105,238   |  |  |  |  |  |  |  |
| Wind                                    | 34,450    |  |  |  |  |  |  |  |
| Solar Thermal and Photovoltaic          | 612       |  |  |  |  |  |  |  |
| Wood and Wood Derived Fuels[6]          | 39,014    |  |  |  |  |  |  |  |
| Geothermal                              | 14,637    |  |  |  |  |  |  |  |
| Other Biomass[7]                        | 16,525    |  |  |  |  |  |  |  |
| Pumped Storage[8]                       | -6,896    |  |  |  |  |  |  |  |
| Other[9]                                | 12,231    |  |  |  |  |  |  |  |
| All Energy Sources                      | 4,156,745 |  |  |  |  |  |  |  |



### Major power generation techniques need turbine engines

2007 Energy Generation Statistics (DOE)



## Motivation – need for wireless strain sensors

- Many parts in turbine engines subjected to severe strain/stress in extreme environments
- Strain sensors
- Predict the failure
- Reduce unnecessary out-of-service examination and replacement
- Moving parts/hidden areas need wireless
- High temperatures need passive





# State of the Art

- Optical-Based Non-Contact Sensors
  - $\Box$  Lack of necessary accuracy
  - □ Not robust in harsh environments
- Strain gage
  - □ Piezoresistivity changes in resistivity with strain/stress
  - □ Cannot be wireless
- Piezoelectric based load cell
  - $\Box$  Can be wireless
  - □ Piezoelectric materials cannot be used to high temperatures
- Capacitive based pressure sensor
  - □ Can measure pressure induced strain/stress
  - □ Cannot measure strain/stress of parts



# **Objectives**

Overall Objective

Develop wireless passive polymer-derived ceramic strain/stress sensors based on cavity RF resonator

- Scientific Goals
  - □ Develop piezo-dielectric polymer-derived ceramics (p-PDCs)
  - Design and fabricate resonator sensors
  - □ Characterize the sensors in extreme environments







## Background – polymer-derived ceramics



- Excellent high-temperature resistance
  - □ High thermal stability
  - □ Excellent high-temperature mechanical properties
  - □ High oxidation/corrosion resistance
- Microfabrication capability
- Unique electric/dielectric behavior
  - □ Resistivity varied in a large range
  - □ High piezoresistivity
  - □ High piezo-dielectricity



## **Schedule and Timeline**

|  | 10/2011-09/2012 |    |    | 10/2012-09/2013 |    |    | 10/2013-09/2014 |    |    |     |     |     |
|--|-----------------|----|----|-----------------|----|----|-----------------|----|----|-----|-----|-----|
|  | Q1              | Q2 | Q3 | Q4              | Q5 | Q6 | Q7              | Q8 | Q9 | Q10 | Q11 | Q12 |
| Task 1: Research<br>Management Plan      |                 |    |    |                 |    |    | 1               |    |    |     |     |     |
| Task 2: Materials development            |                 |    |    |                 |    |    |                 |    |    |     |     |     |
| Task 3: Sensor design<br>and Fabrication |                 |    |    |                 |    |    | 1               |    |    |     |     |     |
| Task 4: Sensor testing                   |                 |    |    |                 |    |    |                 |    |    |     |     |     |

| Milestone   | Planned Completion Date | Verification Method |          |
|---|-------------------------|---------------------|----------|
| <br>1: Finish room temperature material selection | 06/30/2012              | Report              |          |
| 2: Finish first run of sensor design              | 09/30/2012              | Report              | Finished |
| 3: Finish final material selection                | 03/31/2013              | Report              |          |
| 4: Finish final sensor design                     | 09/30/2013              | Report              |          |
| 5: Sensor fabrication                             | 12/31/2013              | Report              |          |
|   |                         | Prototype           |          |
| 6: Sensor characterization                        | 09/30/2014              | Report              |          |
|   |                         | Prototype           |          |



## Accomplishments

- Material development
  - □ Starting chemicals
  - Polysilazane (HTT1800) main precursor
  - Phenylbis (2, 4, 6-trimethylbenzoyl) phosphine oxide (819) photo initiator
  - Dicumyl peroxide (DP) thermal initiator
  - Methacrylic Acid (MA) photopolymerization enhancer
  - Aluminum-tri-sec-butoxide (ASB) precursor for Al
  - Poly (melamine-co-formaldehyde) acrylated solution (PVN) -precursor for N



#### SiAlCN ceramic fabrication







#### □Materials synthesized



| Name       | MA    | ASB    | 819   | HTT1800 | PVN    |
|------------|-------|--------|-------|---------|--------|
| <b>S-1</b> | 2 wt% | 5 wt%  | 5 wt% | 78 wt%  | 10 wt% |
| <b>S-2</b> | 2 wt% | 5 wt%  | 5 wt% | 68 wt%  | 20 wt% |
| <b>S-3</b> | 2 wt% | 5 wt%  | 5 wt% | 58 wt%  | 30 wt% |
| <b>S-4</b> | 2 wt% | 10 wt% | 5 wt% | 53 wt%  | 30 wt% |
| <b>S-5</b> | 2 wt% | 20 wt% | 5 wt% | 43 wt%  | 30 wt% |

TCM

| Name        | ASB    | DP    | HTT1800 |
|-------------|--------|-------|---------|
| <b>S-6</b>  | 5 wt%  | 5 wt% | 90 wt%  |
| <b>S-7</b>  | 1 wt%  | 0 wt% | 99 wt%  |
| <b>S-8</b>  | 5 wt%  | 0 wt% | 95 wt%  |
| <b>S-9</b>  | 10 wt% | 0 wt% | 90 wt%  |
| <b>S-10</b> | 1 wt%  | 2 wt% | 97 wt%  |



#### Dielectric property measurements



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|                                   | rties          |                        | <b>~</b> | >_                  | ~~ -   |  |        |                            |
|-----------------------------------|----------------|------------------------|----------|---------------------|--|--|--------|----------------------------|
|                                   |                | PC                     | N        | Т                   | CM   |  |        |                            |
| Name                              | S-1            | S-2                    | S-3      | S-6                 | <b>S-7</b>   | S-8  | S-9    | S-10                       |
| Dielectric<br>constant            | 4.87           | 6.66                   | 7.40     | 4.45                | 3.6  | 3.55   | 3.85   | 4.8                        |
| Dielectric loss                   | 0.042          | 0.083                  | 0.21     | 0.0085              | 0.0045   | 0.0046   | 0.0046 | 0.0045                     |
| Frequency<br>(GHz)                | 9.767          | 9.743                  | 9.718    | 8.826               | 9.028  | 9.221  | 9.337  | 9.0035                     |
| Q-factor                          | 1452           | 978                    | 445      | 557                 | 1126   | 1370   | 1676   | 1386                       |
| High E<br>Low F<br>Easy to detect |                | 7.5 0.7                |          |                     | <ul> <li>Dielectric cons</li> <li>Dielectric loss</li> </ul> | e 0.25<br>0.20<br>0.15<br>0.10<br>0.05<br>0.008<br>0.008 | Hig    | چ<br>gh <b>٤</b><br>v loss |
| High S-to-N<br>Easy to det        | N ratio<br>ect | 3.5 -<br>-<br>-<br>S-1 | S-2 S-3  | S-6 S-7<br>Sample # | S-8 S-9  | -■<br>- 0.004<br>  |        | 13                         |





Factors that affect the Q-factor:
✓ Thickness of metal skin
✓ Size of the substrat (Lc and Wc)
✓ Size of the slot (La and Wa)

✓ Position of the slot (Xa)



□ Effect of metal skin thickness



#### Metal skin thickness has no effect on Q-factor when it > 20 $\mu$ m



□ Effect of geometries of the slots and substrate



Q<sub>L</sub>: Loaded Q-factor, considered overall effect
Q<sub>r</sub>: Radiation Q-factor, from slot antenna
Q<sub>v</sub>: unloaded Q-factor, dielectric ceramic and metal loss



**Effect** of geometries of the slots and substrate

$$Q_{L}$$

$$Q_{L} = \frac{f_{0}}{\Delta f_{3dB}} \frac{1}{1 - mag(S_{21}(\omega_{0}))} \quad f_{0} = \frac{1}{2\pi\sqrt{\varepsilon_{0}\mu_{0}\varepsilon_{r}}} \frac{\chi_{01}}{r}$$

$$Q_{U}$$

$$Q_{U} = (\frac{1}{Q_{SICN}} + \frac{1}{Q_{Ag}})^{-1}$$

$$\frac{1}{Q_{r}} = \frac{1}{Q_{L}} - \frac{1}{Q_{u}}$$

Maximum energy coupling:

 $Q_r = Q_U$ 



□ Effect of geometries of the slots and substrate

#### Size and position of slot antenna



✓ Q-factor decreases with increasing L or W – more radiation energy loss

✓ Q-factor increases with increasing Xa



## Future work

- Material development
  - □ Characterize high-temperature material properties
- Design and fabricate sensors
  - □ Final design the resonator based strain sensors
  - □ Fabricate the designed sensors
- Sensor characterization
  - $\Box$  Pack the sensor for testing
  - □ Test the sensors in different temperatures

## **UCF**

## Summary

- Polymer-derived ceramics possess necessary properties for making wireless, passive strain/stress sensors for high-temperature applications.
- We have finished materials selection.
- We have finished initial sensor design.
- The R&D progress follows the proposed schedule.



# THANK YOU!